

## FI201209Q1 SERIES (Multilayer Ferrite Chip Bead-High Current)

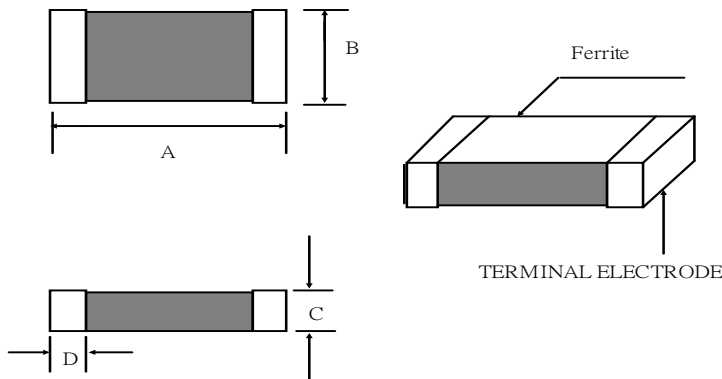
### ●FEATURE

1. Used on high current circuits due to its low
2. High reliability due to an entirely monolithic structure
3. Low DC resistance structure of electrode prevents wasteful electric power consumption
4. Suppress EMI/RFI and to prevent self-oscillation in electronic products
5. AEC-Q200 Grade 1 qualified

### ●Applications

1. Hard drives, Monitors
2. Circuit where a stable ground is unavailable

### ●Shape and Dimension



### ●Specification

Dimension in mm

TYPE	A	B	C	D
FI201209Q1	2.00±0.20	1.25±0.20	0.90±0.20	0.50±0.30

Note1: Test equipment: HP4294A Impedance analyzer

## ●Electrical characteristics

Part Number	Impedance ( $\Omega$ ) at 100MHz	DC Resistance ( $\Omega$ ) Max.	Rated Current (mA) Max.
FI201209Q1U110-3A	11 $\pm$ 25%	0.03	3000
FI201209Q1U170-3A	17 $\pm$ 25%	0.03	3000
FI201209Q1U300-4A	30 $\pm$ 25%	0.04	4000
FI201209Q1U310-3A	31 $\pm$ 25%	0.03	3000
FI201209Q1U470-3A	47 $\pm$ 25%	0.03	3000
FI201209Q1U520-3A	52 $\pm$ 25%	0.03	3000
FI201209Q1U600-3A	60 $\pm$ 25%	0.04	3000
FI201209Q1U800-3A	80 $\pm$ 25%	0.04	3000
FI201209Q1U800-6A	80 $\pm$ 25%	0.02	6000
FI201209Q1U101-4A	100 $\pm$ 25%	0.02	4000
FI201209Q1U121-3A	120 $\pm$ 25%	0.05	3000
FI201209Q1U151-3A	150 $\pm$ 25%	0.05	3000
FI201209Q1U181-4A	180 $\pm$ 25%	0.08	4000
FI201209Q1U201-4A	200 $\pm$ 25%	0.05	4000
FI201209Q1U301-3A	300 $\pm$ 25%	0.05	3000
FI201209Q1U301-4A	300 $\pm$ 25%	0.03	4000
FI201209Q1U331-1.5A	330 $\pm$ 25%	0.07	1500
FI201209Q1U471-3A	470 $\pm$ 25%	0.10	3000
FI201209Q1U601-1A	600 $\pm$ 25%	0.30	1000
FI201209Q1U102-1A	1000 $\pm$ 25%	0.30	1000
FI201209Q1U102-1.5A	1000 $\pm$ 25%	0.30	1500

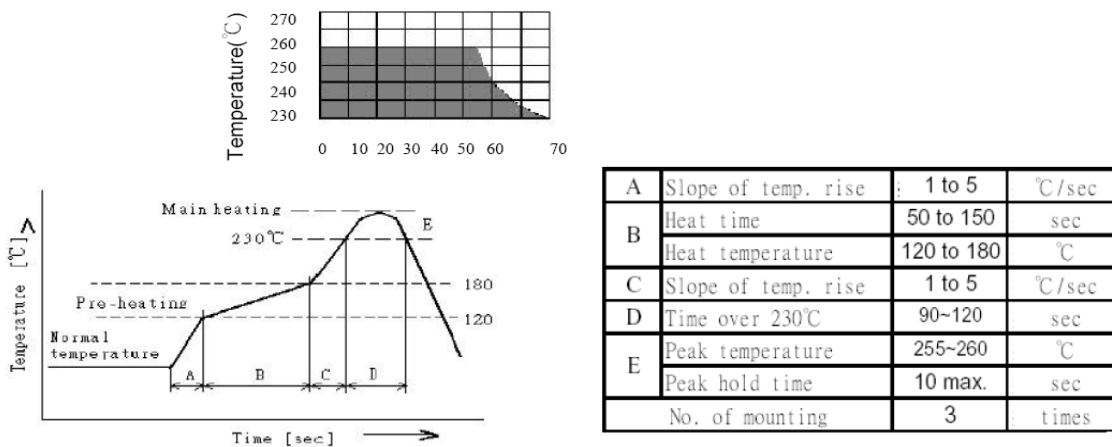
● Reliability Test

1. Reflow soldering conditions

Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 125°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.

Unenough pre-heating may cause cracks on the ferrite, resulting in the deterioration of product quality. Products should be soldered within the following allowable range indicated by the slanted line.

The excessive soldering conditions may cause the corrosion of the electrode, When soldering is repeated, allowable time is the accumulated time.



1.1 Reworking with soldering iron

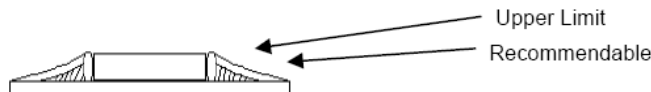
Preheating	150°C, 1minute
Tip temperature	280°C max
Soldering time	3seconds max.
Soldering iron output	30w max.
End of soldering iron	∅ 3mm max.

- Reworking should be limited to only one time.

Note : Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

1.2 Solder Volume

Solder shall be used not to be exceed the upper limits as shown below.

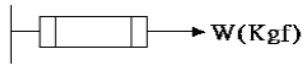
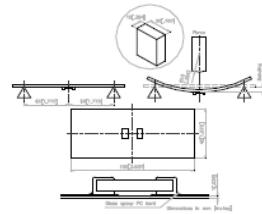



Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

2. IMPEDANCE

2.1 Impedance shall be measured with HP – 4291A impedance analyzer or equivalent system

1. MECHANICAL CHARACTERISTICS

ITEM	REQUIREMENTS	TEST CONDITIONS
TERMINAL STRENGTH	THE TERMINAL ELECTRODE AND THE FERRITE MUST NOT BE DAMAGED BY THE FORCE APPLIED ON THE RIGHT CONDITIONS.	AFTER SOLDERING A LEAD WIRE TO A TERMINAL ELECTRODE, APPLY A LOAD POWER IN THE ARROW DIRECTION. 
FLEXURE STRENGTH	THE TERMINAL ELECTRODE AND THE FERRITE MUST NOT BE DAMAGED BY THE FORCE APPLIED ON THE RIGHT CONDITIONS.	AFTER SOLDERING A CHIP TO A TEST SUBSTRATE, BEND THE SUBSTRATE BY 2m/m AND THEN RETURN. 
BODY STRENGTH	THE FERRITE SHALL NOT BE DAMAGED BY FORCES APPLIED ON THE RIGHT SPECIFICATION $\geq 1.0W(Kgf)$	<b>R0.5mm</b> <b>1.0mm</b>  A : 0.9(mm) 0.04 (INCHES)
RESISTANCE TO SOLDER HEAT	THE CHIPS MUST HAVE NO CRACKS. MORE THAN 75% OF THE TERMINAL ELECTRODE MUST BE COVERED WITH NEW SOLDER. IMPEDANCE & RDC SHALL BE WITHIN $\pm 30\%$ OF THE INITIAL VALUE. INDUCTANCE: WITHIN $\pm 20\%$ OF INITIAL VALUE.	PREHEAT TEMP : 100 TO 150°C PREHEAT TIME : 1 MINUTE SOLDER TEMP : 275 $\pm$ 5°C DIPPING TIME : 5 $\pm$ 1sec
SOLDER ABILITY	MORE THAN 90% OF THE TERMINAL ELECTRODES SHALL BE COVERED WITH NEW SOLDER.	PREHEAT TEMP : 100 TO 150°C PREHEAT TIME : 1 MINUTE SOLDER TEMP : 215 $\pm$ 5°C DIPPING TIME : 3 $\pm$ 1sec

4. RELIABILITY AND TEST CONDITIONS

4.1 HIGH TEMPERATURE RESISTANCE

a. Performance specification

1. Appearance : no mechanical damage
2. Impedance shall be with  $\pm 30\%$  of the initial value

b. Test condition

1. Temperature 125°C  $\pm$  2°C
2. Applied current : Rated current
3. Testing time : 1008 $\pm$ 12hrs (maximum value)
4. Measurement : After placing at room ambient temperature for 24 hours minimum

4.2 HUMIDITY RESISTANCE

a. Performance specification

1. Appearance : no mechanical damage
  2. Impedance shall be with  $\pm 30\%$  of the initial value
- b. Test condition
1. Humidity : 90 to 95% RH
  2. Temperature :  $40 \pm 2^\circ\text{C}$
  3. Applied current : Rated current (maximum value)
  4. Testing time :  $1008 \pm 12$  hours
  5. Measurement : After placing at room ambient temperature for 24 hours minimum

#### 4.3 TEMPERATURE CYCLE

- a. Performance specification
1. Appearance : no mechanical damage
  2. Impedance shall be with  $\pm 30\%$  of the initial value
- b. Test condition
1. Temperature  $-55^\circ\text{C}, +125^\circ\text{C}$  kept stabilized for 30 minutes each
  2. Cycle : 100 cycles
  3. Measurement : After placing for 24 hours minimum at room ambient temperature
  4. step1.  $-55^\circ\text{C}$  temp  $\pm 3^\circ\text{C}$   $30 \pm 3$  minutes  
step2. Room temperature 2 to 5 minutes  
step3.  $+125^\circ\text{C}$  temp  $\pm 2^\circ\text{C}$   $30 \pm 3$  minutes  
step4. room temperature 2 to 5 minutes

#### 4.4 LOW TEMPERATURE STORAGE LIFE TEST

- a. Performance specification
1. Appearance : no mechanical damage
  2. Impedance shall be with  $\pm 30\%$  of the initial value
- b. Test condition
1. Temperature  $-55^\circ\text{C} \pm 2^\circ\text{C}$
  2. Testing time :  $1008 \pm 12$  hours
  3. Measurement : After placing for 24 hours minimum at room ambient temperature

#### 5. STORAGE

- 5.1 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Packages must be stored at  $40^\circ\text{C}$  or less and 70% RH or less.
- 5.2 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide).
- 5.3 Packaging material may be deformed if packages are stored where they are exposed to heat or direct sun — light.
- 5.4 Minimum packages, such as polyvinyl heat — seal packages shall not be opened until just before they are used. If opened, use the reels as soon as possible.

5.5 Solderability specified in composite specification page.3 shall be for 12 months from the date of delivery on condition that they are stored at the environment specified clause 5-1 & 5-2.

For those parts which passed more than 12 months shall be checked solderability before it is used.